

EAST - [10657490B.wsp:1]

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Drafts  
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 L5: (989) ((MIM or Metal-Insulator-Metal or Metal adj Insulator adj Metal) near capacitor  
 L6: (242) ((MIM or Metal-Insulator-Metal or Metal adj Insulator adj Metal) near capacitor) and (...  
 L7: (47) ((MIM or Metal-Insulator-Metal or Metal adj Insulator adj Metal) near capacitor) and fi...  
 L8: (10) ((MIM or Metal-Insulator-Metal or Metal adj Insulator adj Metal) near capacitor) and fi...  
 L9: (79) ((MIM or Metal-Insulator-Metal or Metal adj Insulator adj Metal) near capacitor) and (...  
 L10: (1) 9 and (landing adj pad adj type adj independent adj interconnection)  
 L11: (1) 5 and (landing adj pad adj type adj independent adj interconnection)  
 L12: (1) 5 and (independent adj interconnection)  
 Failed  
 (0) ((MIM or Metal-Insulator-Metal or Metal adj Insulator adj Metal) near capacitor) and (first...  
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 Default open Highlight all hit terms initially

((MIM or Metal-Insulator-Metal or Metal adj Insulator adj Metal) near capacitor) and ((intermetal near dielectric) or (intermetal adj dielectric) or IMD or (inter-metal adj dielectric))

ABR... A is 23m 25 Text 25 H

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20040115850 A1	20040617	20	A MICRODISPLAY PIXEL CELL AND METHOD OF MAKING IT	438/30	349/43; 438/239
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113190 A1	20040617	19	Integrated circuit devices including a MIM capacitor	257/296	
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20040087101 A1	20040506	14	High K artificial lattices for capacitor applications to use in CU or AL BEOL	438/396	438/240; 438/638
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20040087098 A1	20040506	14	MIM AND METAL RESISTOR FORMATION AT CU BEOL USING ONLY ONE EXTRA	438/381	
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20040084712 A1	20040506	12	Scaled EEPROM cell by metal-insulator-metal (MIM) coupling	257/314	438/257
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20040084707 A1	20040506	9	Finger metal-insulator-metal capacitor device with local interconnect	257/301	257/E21.018
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20040077141 A1	20040422	9	Capacitor and fabrication method thereof	438/240	
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20040072406 A1	20040415	13	Structure and process for a capacitor and other devices	438/396	
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20040009646 A1	20040115	19	Low temperature MIM capacitor for mixed-signal/RF applications	438/381	
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20030234415 A1	20031225	10	Scalable three-dimensional fringe capacitor with stacked via	257/303	
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20030219983 A1	20031127	11	Method of forming a MIM capacitor structure	438/694	